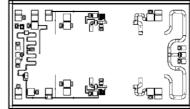
AMT2112 9 – <u>14GHz Power Amplifier Chip</u>



Key Features :

- Frequency : 9 14GHz
- Typical small signal gain : 30dB
- Typical output power : 43.5dBm
- Typical power added efficiency : 33%
- Supply voltage : 28V, -2V
- Chip dimensions : 4.05mm x 2.35mm x 0.1mm
- Applications : wireless communication, transceiver module, radio telecommunication etc.

Description:

AMT2112 chip is a high performance high efficiency 9 – 14GHz power amplifier, it is designed based on Gallium Nitrate (GaN) HEMT process, with ground through metal via on the back technology. All chip products are 100% RF tested. AMT2112 is with dual voltage supply, drain voltage Vds at 28V, it provides 43.5dBm output power in 9 – 14GHz frequency range.

Symbol	Parameter	Value	Remark					
Vd	Drain Voltage	35V						
Id	Drain Current	4A						
Vg	Gate Voltage	-1.6V						
lg	Gate Current	150mA						
Pd	DC Power Consumption	100W						
Pin	Input Signal Power	30dBm						
Tch	Operating Temperature	150°C						
Tm	Sintering Temperature	310°C	30s, N ₂ protection					

Absolute Maximum Ratings (Ta = 25°C)

[1] Operation outside any of the Absolute Maximum Ratings may cause permanent device damage.

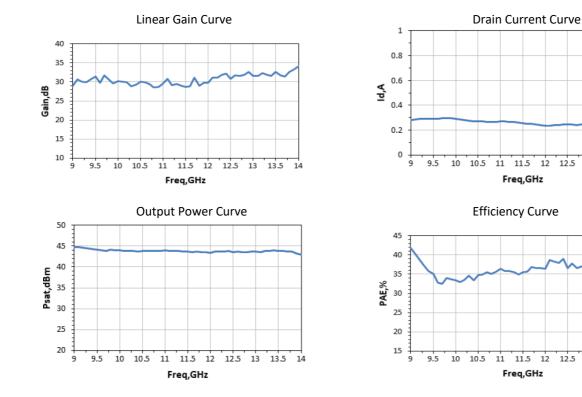
Electrical Characteristics (Ta = 25°C)

Symbol	Parameter	Test Condition	Value		Unit	
			Min	Typical	Max	
Gain	Small Signal Gain		-	30	-	dB
VSWRin	Input SW	Vd = 28V	-	1.8	2	dB
Pout	Saturated Output Power	Vg = -2V	-	43.5	-	dBm
PAE	Power Added Efficiency	F : 9~14GHz	-	33	-	%
Id	Operating Current	Duty Cycle : 10%	-	2.4	3	A

Note, under non-CW operation.

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Typical Performance



12 12.5

12.5

12

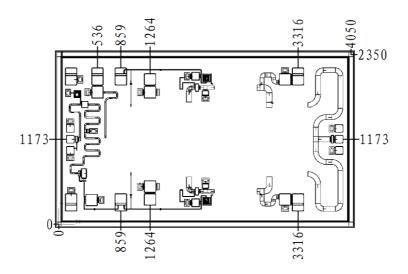
13 13.5 14

13 13.5

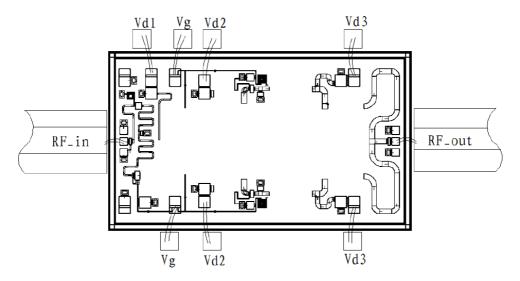
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Chip Dimension (Unit : µm)



Chip Layout Diagram



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Pad Delinition							
Symbol	Function	Dimension	Equivalent Circuit				
RF_in	RF signal input port, connecting to external 50 Ω system. DC blocking capacitor is needed, if external DC current is applied to this pad.	100*100µm²	RF₋in ↔				
RF_out	RF signal output port, connecting to external 50 Ω system, no need to add DC blocking capacitor.	100*100µm²	- ↓ RF_out				
Vg	Amplifier gate bias, need external 100pF, 1000pF capacitor.	150*230μm²	Vg HHLJ				
Vd1	Amplifier drain bias, need external 100pF, 1000pF capacitor.	150*230μm²					
Vd2	Amplifier drain bias, need external 100pF, 1000pF capacitor.	150*150μm²					
Vd3	Amplifier drain bias, need external 100pF, 1000pF capacitor.	150*230μm²					

Pad Definition

Refer to Appendix A for details.